

DZ2S180C0L Silicon epitaxial planar type

For ESD protection Bi-directional type

- Features
- High ESD
- Low terminal capacitance Ct
- Halogen-free / RoHS compliant (EU RoHS / UL-94 V-0 / MSL:Level 1 compliant)
- Marking Symbol: YH

Packaging

Embossed type (Thermo-compression sealing): 3 000 pcs / reel (standard)

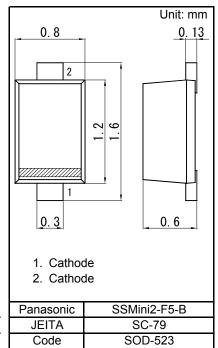
■ Absolute Maximum Ratings Ta = 25 °C

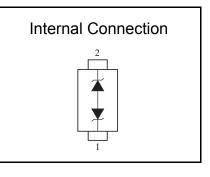
Parameter	Symbol	Rating	Unit
Total power dissipation *1	PT	150	mW
Electrostatic discharge ^{*2}	ESD	±15	kV
Junction temperature	Tj	150	°C
Operating ambient temperature	Topr	-40 to +85	°C
Storage temperature	Tsta	-55 to +150	℃

Note) *1 Mounted on glass epoxy print board (45 mm × 45 mm × 1 mm) Solder in (0.8 mm × 0.6 mm)

*2 Test method : IEC61000_4_2

(C = 150 pF, R = 330 Ω , Contact discharge : 10 times)





■ Electrical Characteristics Ta = 25 °C ± 3 °C

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Parameter	Symbol	Conditions	Min	Тур	Max	Unit	
Zener voltage *1, *2	VZ	IZ = 5 mA	17.5		20.0	V	
Zener operating resistance	RZ	IZ = 5 mA			60	Ω	
Reverse current	IR	VR = 13 V			15	nA	
Terminal capacitance	Ct	VR = 0 V, f = 1 MHz		5		pF	
Temperature coefficient of zener voltage *3	SZ	IZ = 5 mA		14		mV/°C	
Note) 4. Macautics mothed and handless INDUCTRIAL CTANDARD, U.O. 7004 Macautics mothed for Diades							

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 Measuring methods for Diodes.

2. *1 The temperature must be controlled 25 °C for VZ mesurement.

VZ value measured at other temperature must be adjusted to VZ (25 °C).

*2 VZ guaranted 20 ms after current flow

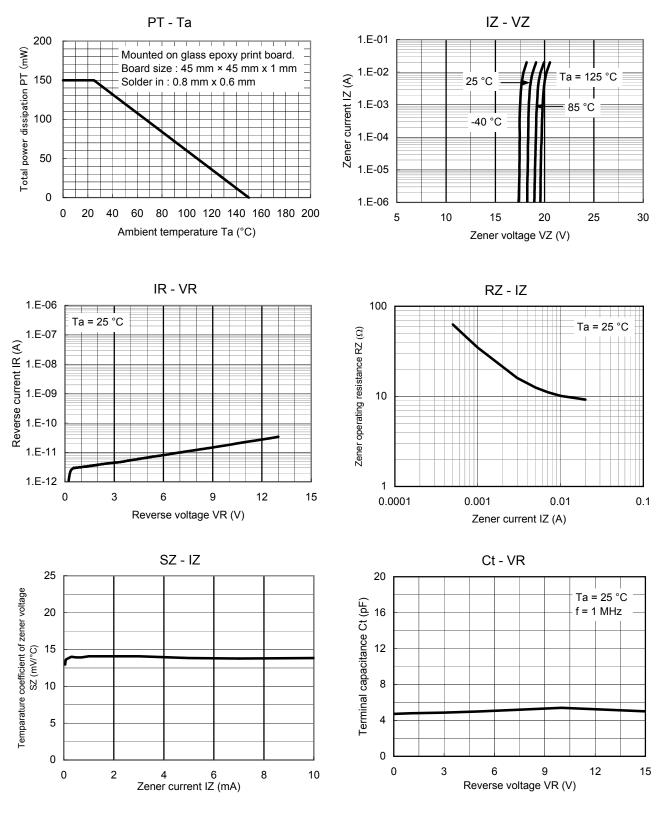
*3 Tj = 25 °C to 150 °C

Zener Diode DZ2S180C0L



Zener Diode DZ2S180C0L

Technical Data (reference)



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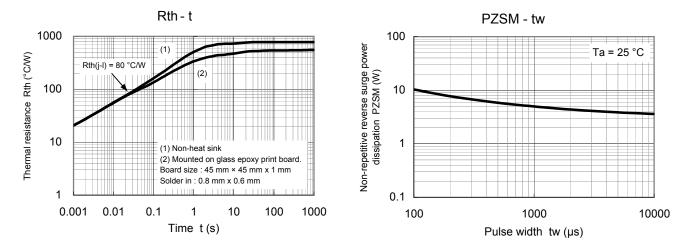
Established : 2010-05-27 Revised : 2013-07-24

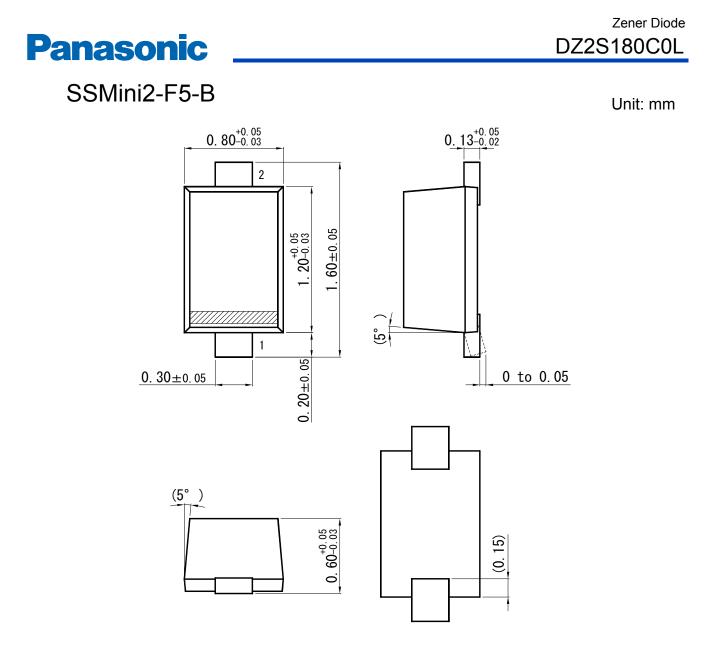




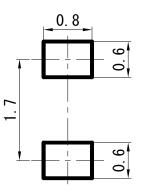
Zener Diode DZ2S180C0L

Technical Data (reference)





Land Pattern (Reference) (Unit: mm)



Established : 2010-05-27 Revised : 2013-07-24

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